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March 2013

FAN73711 High-Current, High-Side Gate Drive IC

Features

- Floating Channel for Bootstrap Operation to +600 V
- 4 A / 4 A Sourcing/Sinking Current Driving Capability
- Common-Mode dv/dt Noise Canceling Circuit
- 3.3 V and 5 V Input Logic Compatible
- Output In-phase with Input Signal
- Under-Voltage Lockout for V_{BS}
- Built-In Shunt Regulator on V_{DD} and V_{BS}
- 8-Lead, Small Outline Package (SOP)

Applications

- High-Speed Gate Driver
- Sustain Switch Driver in PDP Application
- Energy Recovery Circuit Switch Driver in PDP Application
- High-Power Buck Converter
- Motor Drive Inverter

Description

The FAN73711 is a monolithic high-side gate-drive IC that can drive high-speed MOSFETs and IGBTs operating up to +600 V. It has a buffered output stage with all NMOS transistors designed for high pulse-current driving capability and minimum cross-conduction.

Fairchild's high-voltage process and common-mode noise canceling techniques provide stable operation of the high-side driver under high dv/dt noise circumstances. An advanced level-shift circuit offers high-side gate driver operation up to V_S =-9.8 V (typical) for V_{BS} =15 V. The UVLO circuit prevents malfunction when V_{BS} is lower than the specified threshold voltage.

The high-current and low-output voltage-drop feature makes this device suitable as a sustain and energy-recovery circuit switch driver in plasma display panel, motor drive inverter, switching power supply, and high-power DC-DC converter applications.

8-SOP



Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method		
FAN73711MX	40°C ~ 125°C	8-SOP	Tape and Reel		

Typical Application Diagrams

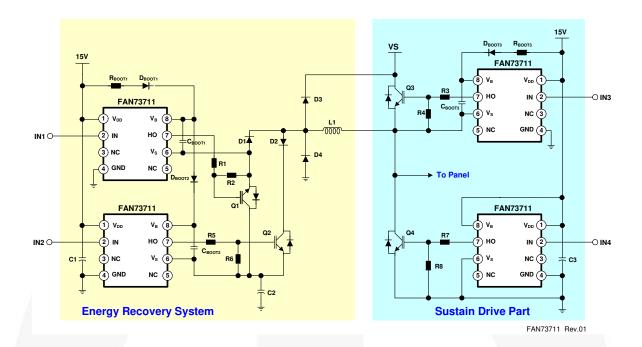


Figure 1. Floated Bi-Directional Switch and Half-Bridge Driver: PDP Application

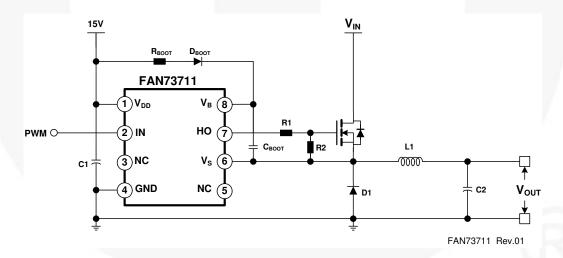
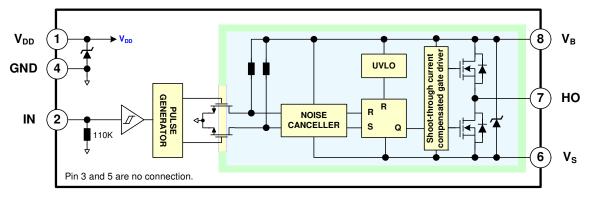


Figure 2. Step-Down (Buck) DC-DC Converter Application

Internal Block Diagram



FAN73711 Rev.01

Figure 3. Functional Block Diagram

Pin Configuration

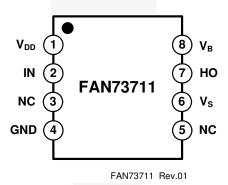


Figure 4. Pin Configuration (Top View)

Pin Definitions

Pin #	Name	Description
1	V _{DD}	Supply Voltage
2	IN	Logic Input for High-Side Gate Driver Output
3	NC	No Connection
4	GND	Ground
5	NC	No Connection
6	V _S	High-Voltage Floating Supply Return
7	НО	High-Side Driver Output
8	V _B	High-Side Floating Supply

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. $T_A=25^{\circ}C$ unless otherwise specified.

Symbol	Characteristics	Min.	Max.	Unit
V _S	High-Side Floating Offset Voltage ⁽¹⁾	V _B -V _{SHUNT}	V _B +0.3	V
V _B	High-Side Floating Supply Voltage	-0.3	625.0	V
V _{HO}	High-Side Floating Output Voltage	V _S -0.3	V _B +0.3	V
V _{DD}	Low-Side and Logic Supply Voltage ⁽¹⁾	-0.3	V _{SHUNT}	V
V _{IN}	Logic Input Voltage	-0.3	V _{DD} +0.3	V
dV _S /dt	Allowable Offset Voltage Slew Rate		± 50	V/ns
P _D	Power Dissipation ^(2,3,4)		0.625	W
$\theta_{\sf JA}$	Thermal Resistance		200	°C/W
T _J	Junction Temperature	-55	+150	°C
T _{STG}	Storage Temperature	-55	+150	°C

Notes:

- This IC contains a shunt regulator on V_{DD} and V_{BS}. This supply pin should not be driven by a low-impedance voltage source greater than the V_{SHUNT} specified in the Electrical Characteristics section.
- 2. Mounted on 76.2 x 114.3 x 1.6 mm PCB (FR-4 glass epoxy material).
- Refer to the following standards: JESD51-2: Integral circuits thermal test method environmental conditions, natural convection, and JESD51-3: Low effective thermal conductivity test board for leaded surface-mount packages.
- 4. Do not exceed power dissipation (P_D) under any circumstances.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V _B	High-Side Floating Supply Voltage	V _S +10	V _S +20	V
V_S	High-Side Floating Supply Offset Voltage	6-V _{DD}	600	V
V _{HO}	High-Side Output Voltage	V _S	V_{B}	V
V _{IN}	Logic Input Voltage	GND	V_{DD}	V
V _{DD}	Supply Voltage	10	20	V
T _A	Operating Ambient Temperature	-40	+125	°C

Electrical Characteristics

 $V_{BIAS}(V_{DD}, V_{BS})$ =15.0 V, T_A = 25°C, unless otherwise specified. The V_{IN} and I_{IN} parameters are referenced to GND. The V_O and I_O parameters are relative to V_S and are applicable to the respective output HO.

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
Power S	upply Section	1	1	1	1	
I _{QDD}	Quiescent V _{DD} Supply Current	V _{IN} =0 V or 5 V		25	70	μА
I _{PDD}	Operating V _{DD} Supply Current	f _{IN} =20 kHz, No Load		35	100	μΑ
Bootstra	pped Supply Section			ı	l	
V _{BSUV+}	V _{BS} Supply Under-Voltage Positive-Going Threshold Voltage	V _{BS} =Sweep	8.0	9.0	10.0	V
V _{BSUV} -	V _{BS} Supply Under-Voltage Negative-Going Threshold Voltage	V _{BS} =Sweep	7.3	8.3	9.3	V
V _{BSHYS}	V _{BS} Supply Under-Voltage Lockout Hysteresis Voltage	V _{BS} =Sweep		0.7		٧
I _{LK}	Offset Supply Leakage Current	V _B =V _S =625 V			10	μΑ
I _{QBS}	Quiescent V _{BS} Supply Current	V _{IN} =0V or 5 V		60	120	μΑ
I _{PBS}	Operating V _{BS} Supply Current	C _{LOAD} =1000 pF, f _{IN} =20 kHz, rms Value		470	800	μА
Shunt R	egulator Section			ı		
V _{SHUNT}	V _{DD} and V _{BS} Shunt Regulator Clamping Voltage	V _{DD} =Sweep or V _{BS} =Sweep I _{SHUNT} =5 mA	21	23	25	V
Input Lo	gic Section	SHOW				
V _{IH}	Logic "1" Input Voltage		2.5			V
V _{IL}	Logic "0" Input Voltage				0.8	V
I _{IN+}	Logic Input High Bias Current	V _{IN} =5 V		40	65	μΑ
I _{IN-}	Logic Input Low Bias Current	V _{IN} =0 V			2	μΑ
R _{IN}	Input Pull-Down Resistance		90	110		ΚΩ
Gate Dri	ver Output Section					
V _{OH}	High Level Output Voltage (V _{BIAS} - V _O)	No Load			1.2	V
V _{OL}	Low Level Output Voltage	No Load			30	mV
I _{O+}	Output High, Short-Circuit Pulsed Current ⁽⁵⁾	V _{HO} =0 V, V _{IN} =5 V, PW ≤10 μs	3	4		Α
I _{O-}	Output Low, Short-Circuit Pulsed Current ⁽⁵⁾	V _{HO} =15 V,V _{IN} =0 V, PW ≤10 μs	3	4	Ţ	Α
V_S	Allowable Negative V _S Pin Voltage for IN Signal Propagation to HO			-9.8	-7.0	٧

Note:

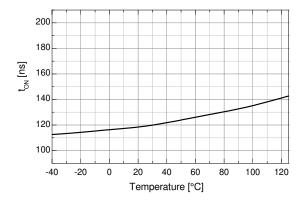
5. These parameters guaranteed by design.

Dynamic Electrical Characteristics

 $\rm V_{DD}{=}V_{BS}{=}15~V,~GND{=}0~V,~C_{LOAD}{=}1000~pF,~T_{A}{=}25^{\circ}C,~unless~otherwise~specified.$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
t _{on}	Turn-On Propagation Delay	V _S =0 V		150	210	ns
t _{off}	Turn-Off Propagation Delay	V _S =0 V		150	210	ns
t _r	Turn-On Rise Time			25	50	ns
t _f	Turn-Off Fall Time			15	40	ns

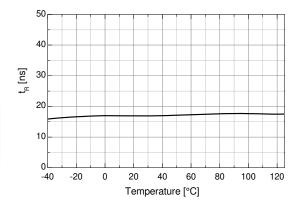
Typical Characteristics



200 180 180 140 120 140 120 100 -40 -20 0 20 40 60 80 100 120 Temperature [°C]

Figure 5. Turn-On Propagation Delay vs. Temperature

Figure 6. Turn-Off Propagation Delay vs. Temperature



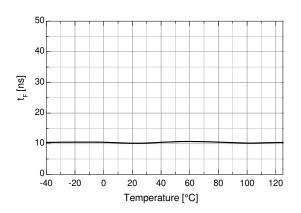
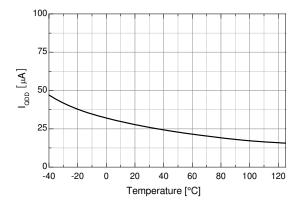


Figure 7. Turn-On Rise Time vs. Temperature

Figure 8. Turn-Off Fall Time vs. Temperature



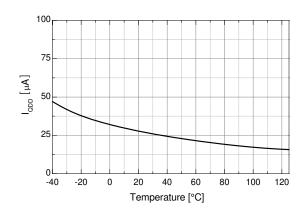
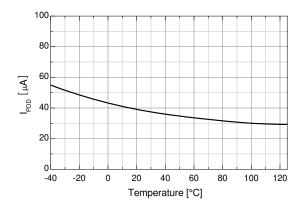


Figure 9. Quiescent V_{DD} Supply Current vs. Temperature

Figure 10. Quiescent V_{BS} Supply Current vs. Temperature

Typical Characteristics (Continued)



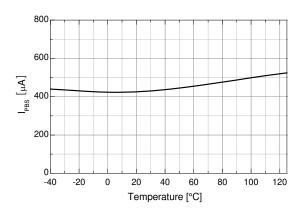
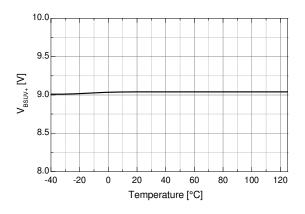


Figure 11. Operating V_{DD} Supply Current vs. Temperature

Figure 12. Operating V_{BS} Supply Current vs. Temperature



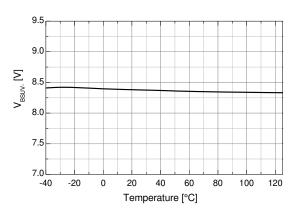
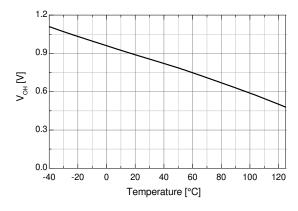


Figure 13. V_{BS} UVLO+ vs. Temperature

Figure 14. V_{BS} UVLO- vs. Temperature



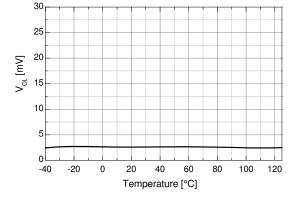
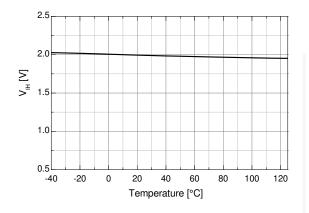


Figure 15. High-Level Output Voltage vs. Temperature

Figure 16. Low-Level Output Voltage vs. Temperature

Typical Characteristics (Continued)



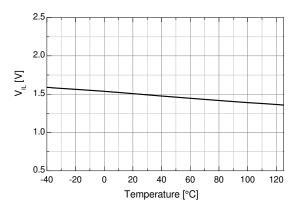
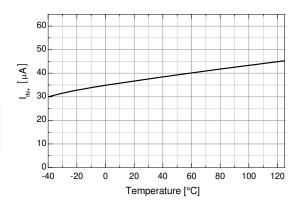


Figure 17. Logic High Input Voltage vs. Temperature

Figure 18. Logic Low Input Voltage vs. Temperature



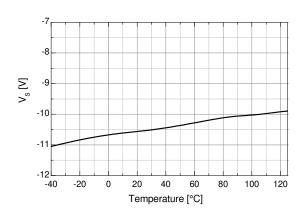


Figure 19. Logic Input High Bias Current vs. Temperature

Figure 20. Allowable Negative V_S Voltage vs. Temperature

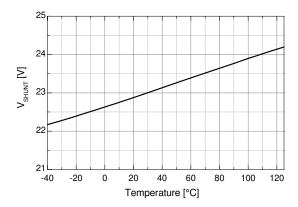


Figure 21. Shunt Regulator Clamping Voltage vs. Temperature

Switching Time Definitions

Timing Diagram

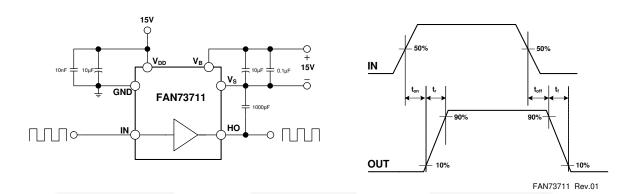


Figure 22. Switching Time Test Circuit and Waveform Definitions

Package Dimensions 1.27 0.65 1.75 5.60 6.30 5.70 3.75 PIN #1 ID 1.27 (0.35) \oplus 0.25 M C B A LAND PATTERN RECOMMENDATION **TOP VIEW** 1.80 1.35 1.75 С (8X) **OPTION A - BEVEL EDGE** ○ 0.10 C **FRONT VIEW OPTION B - NON BEVEL EDGE** NOTES: UNLESS OTHERWISE SPECIFIED BEVEL A. THIS PACKAGE CONFORMS TO JEDEC MS-012 **GAUGE** VARIATION A EXCEPT WHERE NOTED. R0.10 **PLANE** B. ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 **SEATING** OUT OF JEDEC STANDARD VALUE **PLANE** D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS. E. LAND PATTERN AS PER IPC SOIC127P600X175-8M 4°-8° F. FILE NAME: MKT-M08B REV1 0.80 0.30 (1.04) **DETAIL "B"** SCALE 2:1

Figure 23. 8-Lead Small Outline Package (SOP)

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